ABSTRACT

There is disclosed a magnetic head device in which a head IC chip may be located relatively closer to a magnetic head and a thermal effect may be controlled to be within a range of acceptable degree. Said magnetic head device comprises a head slider having a magnetic head, a suspension member which is made of thin resilient material and supports the head slider at one end thereof, and a head IC chip, wherein the suspension member is attached to other member at the other end thereof. The IC chip is mounted on the suspension member. When the IC chip is selected to have appropriate disc side area and is mounted on the suspension member, the temperature of the IC chip itself may be maintained within a range of acceptable degree and that of the magnetic head may be also kept to be lower. When the electric power consumption of the IC chip is equal to or less than 410 mW, the disc side area thereof should be equal to or more than 1.1 mm^2. The IC chip is mounted on a surface of the suspension member at a side facing to the disc at a position where a relative linear velocity equal to or more than 25 m/sec is generated with respect to said disc.

This Sheet Has Been Replaced

